

RoHS Compliance of Products



This is to certify that the product types listed in the enclosed table conform with the

Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive) (last Amendment with Directive 2015/863/EU)

The listed product types do not contain mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB), polybrominated diphenyl ethers (PBDE), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP) and diisobutyl phthalate (DIBP).

But the listed products can contain lead / a lead component which is explained as follows:

Lead (Pb) / lead components:

The sensor types can contain lead in form of lead oxide (PbO) which is combined with / fixed in the glass layers of the sensor element. According to figure 7c-I of the annex of the directive 2011/65/EU the use of "lead in glass of ... electronic components" is exempted from the requirements of Article 4(1) of the directive.

Under consideration of the explained exemption and under consideration of quantity limits for restricted materials the listed product types are in compliance with the EU directive 2011/65/EU.

The declaration is only valid for standard sensor elements. Any change of the listed product types like for example extension with other lead material and/or housing and/or insulation and/or other changes made by Heraeus Sensor Technology GmbH and/or made by the customer itself requires a new evaluation of the final sensor type / article for compliance with the RoHS directive.

Heraeus Sensor Technology GmbH

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Quality Manager

Table of standard sensor elements

| Type | Connection Material | RoHS exemption | Type | Connection Material | RoHS exemption |
|--------------|---------------------------|----------------|--------------|---------------------------|----------------|
| C 220 | AgPd | None | C 416 | AuPd | 7c-I |
| C 420 | AgPd | 7c-I | C 420 | NiPt | 7c-I |
| HL 220 | NiCr-Pt | None | HM 220 | Pd alloy-Pt | None |
| HDA 420 | Pt | None | HD 421 | Pt | None |
| HA 420 | Pt | None | | | |
| L 220 | AgPd | 7c-I | L 410 ax | AgPd | 7c-I |
| L 416 | AgPd | 7c-I | L 420 | AgPd | 7c-I |
| L 540 | AgPd | 7c-I | L 1020 | AgPd | 7c-I |
| LN 222 | NiAg | None | | | |
| M 213 | NiPt | 7c-I | M 219 | NiPt | 7c-I |
| M 220 / 222 | NiPt | 7c-I | M 310 | NiPt | 7c-I |
| M 416 | NiPt | 7c-I | M 419 | NiPt | 7c-I |
| M 422 | NiPt | 7c-I | M 620 | NiPt | 7c-I |
| M 1020 | NiPt | 7c-I | | | |
| MN 220 / 222 | Ni | None | MN 420 / 422 | Ni | None |
| MH 220 | AuPd | None | MH 416 | AuPd | None |
| MH 420 | AuPd | None | | | |
| MR 828 | NiPt | 7c-I | MR 845 | NiPt | 7c-I |
| PCB 1325 | Tinned Cu pads | None | PCB 2225 | Tinned Cu pads | None |
| PCB 2230 | Tinned Cu pads | None | PCB 2236 | Tinned Cu pads | None |
| PCB 2240 | Tinned Cu pads | None | | | |
| SMD-V 0603 | Tinned edge metallization | None | SMD-V 0805 | Tinned edge metallization | None |
| SMD-V 1206 | Tinned edge metallization | None | | | |
| SMD 0603 FC | AgPt metallization | None | SMD 0805 FC | AgPt metallization | None |
| TO92 | Sn plated Cu alloy | 7c-I | SOT 223 | Sn plated Cu alloy | 7c-I |

We reserve the right to make alterations and technical data printed. All data serve as a guideline and do not guarantee particular properties to any product.